

42390.P955



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

#8 *Amend*
P. B. L.
9/4/01
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SEP 11 2001
TC-2880 MAIL ROOM

In re Application of:

Mu, et al.

Serial No.: 09/661,899

Filed: September 14, 2000

For: PROCESS FOR FORMING A
DIRECT BUILD-UP LAYER ON AN
ENCAPSULATED DIE PACKAGE
AND INTERMEDIATE
STRUCTURES FORMED
THEREWITH

Examiner: A. Chambliss

Group Art Unit: 2814

Attorney Docket No.: 42390.P8497

CERTIFICATE OF MAILING

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RESPONSE TO RESTRICTION REQUIREMENT
AND PRELIMINARY AMENDMENT

Hon. Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Restriction Requirement mailed August 3, 2001 and prior to the examination of the claims on the merits, Applicants respectfully request that the Examiner enter the following amendments:

A